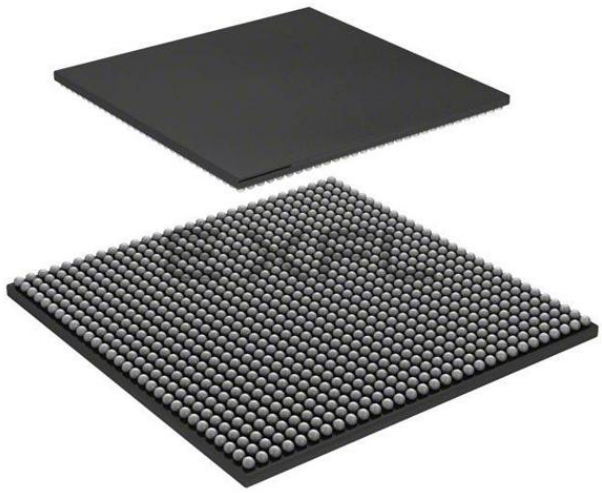
AMD Xilinx - XCV1600E-7FG900I Datasheet



Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	7776
Number of Logic Elements/Cells	34992
Total RAM Bits	589824
Number of I/O	700
Number of Gates	2188742
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1600e-7fg900i

Virtex-E Ordering Information

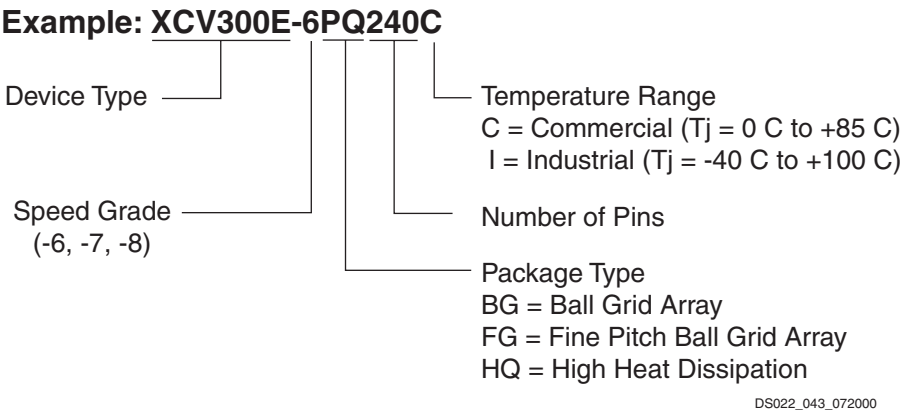


Figure 1: **Ordering Information**

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T_{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V_{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	• Numerous minor edits. • Data sheet upgraded to Preliminary. • Preview -8 numbers added to **Virtex-E Electrical Characteristics** tables.
8/1/00	1.6	• Reformatted entire document to follow new style guidelines. • Changed speed grade values in tables on pages 35-37.
9/20/00	1.7	• Min values added to **Virtex-E Electrical Characteristics** tables. • XCV2600E and XCV3200E numbers added to **Virtex-E Electrical Characteristics** tables (Module 3). • Corrected user I/O count for XCV100E device in Table 1 (Module 1). • Changed several pins to “No Connect in the XCV100E“ and removed duplicate V_{CCINT} pins in Table ~ (Module 4). • Changed pin J10 to “No connect in XCV600E” in Table 74 (Module 4). • Changed pin J30 to “VREF option only in the XCV600E” in Table 74 (Module 4). • Corrected pair 18 in Table 75 (Module 4) to be “AO in the XCV1000E, XCV1600E“.

Architectural Description

Virtex-E Array

The Virtex-E user-programmable gate array, shown in Figure 1, comprises two major configurable elements: configurable logic blocks (CLBs) and input/output blocks (IOBs).

- CLBs provide the functional elements for constructing logic
- IOBs provide the interface between the package pins and the CLBs

CLBs interconnect through a general routing matrix (GRM). The GRM comprises an array of routing switches located at the intersections of horizontal and vertical routing channels. Each CLB nests into a VersaBlock™ that also provides local routing resources to connect the CLB to the GRM.

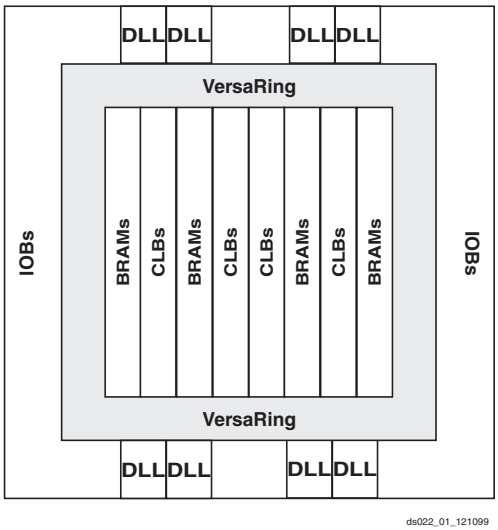


Figure 1: **Virtex-E Architecture Overview**

The VersaRing™ I/O interface provides additional routing resources around the periphery of the device. This routing improves I/O routability and facilitates pin locking.

The Virtex-E architecture also includes the following circuits that connect to the GRM.

- Dedicated block memories of 4096 bits each
- Clock DLLs for clock-distribution delay compensation and clock domain control
- 3-State buffers (BUFTs) associated with each CLB that drive dedicated segmentable horizontal routing resources

Values stored in static memory cells control the configurable logic elements and interconnect resources. These values load into the memory cells on power-up, and can reload if necessary to change the function of the device.

Input/Output Block

The Virtex-E IOB, Figure 2, features SelectI/O+ inputs and outputs that support a wide variety of I/O signalling standards, see Table 1.

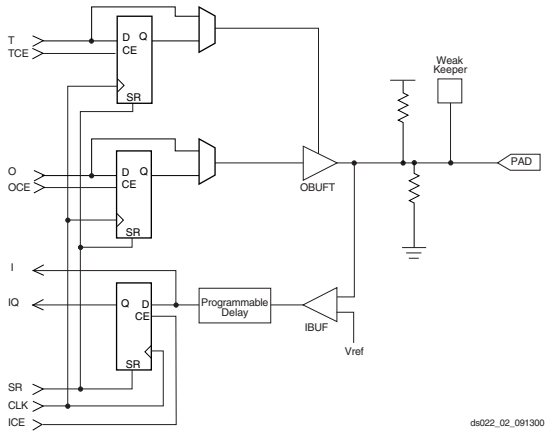


Figure 2: **Virtex-E Input/Output Block (IOB)**

The three IOB storage elements function either as edge-triggered D-type flip-flops or as level-sensitive latches. Each IOB has a clock signal (CLK) shared by the three flip-flops and independent clock enable signals for each flip-flop.

© 2000–2006 Xilinx, Inc. All rights reserved. All Xilinx trademarks, registered trademarks, patents, and disclaimers are as listed at http://www.xilinx.com/legal.htm. All other trademarks and registered trademarks are the property of their respective owners. All specifications are subject to change without notice.

Because any single DLL can access only two BUFGs at most, any additional output clock signals must be routed from the DLL in this example on the high speed backbone routing.

The dll_2x files in the **xapp132.zip** file show the VHDL and Verilog implementation of this circuit.

Virtex-E 4x Clock

Two DLLs located in the same half-edge (top-left, top-right, bottom-right, bottom-left) can be connected together, without using a BUFG between the CLKDLLs, to generate a 4x clock as shown in Figure 30. Virtex-E devices, like the Virtex devices, have four clock networks that are available for internal deskewing of the clock. Each of the eight DLLs have access to two of the four clock networks. Although all the DLLs can be used for internal deskewing, the presence of two GCLKBUFs on the top and two on the bottom indicate that only two of the four DLLs on the top (and two of the four DLLs on the bottom) can be used for this purpose.

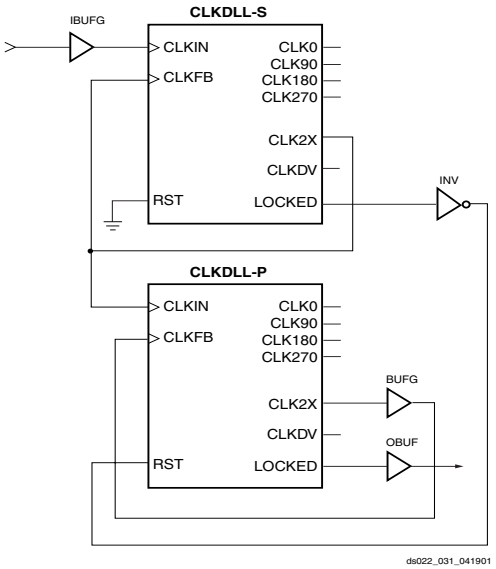


Figure 30: **DLL Generation of 4x Clock in Virtex-E Devices**

The dll_4xe files in the xapp132.zip file show the DLL implementation in Verilog for Virtex-E devices. These files can be found at:

ftp://ftp.xilinx.com/pub/applications/xapp/xapp132.zip

Using Block SelectRAM+ Features

The Virtex FPGA Series provides dedicated blocks of on-chip, true dual-read/write port synchronous RAM, with 4096 memory cells. Each port of the block SelectRAM+ memory can be independently configured as a read/write port, a read port, a write port, and can be configured to a specific data width. The block SelectRAM+ memory offers new capabilities allowing the FPGA designer to simplify designs.

Operating Modes

VIrtex-E block SelectRAM+ memory supports two operating modes:

- Read Through
- Write Back

Read Through (one clock edge)

The read address is registered on the read port clock edge and data appears on the output after the RAM access time. Some memories might place the latch/register at the outputs, depending on whether a faster clock-to-out versus set-up time is desired. This is generally considered to be an inferior solution, since it changes the read operation to an asynchronous function with the possibility of missing an address/control line transition during the generation of the read pulse clock.

Write Back (one clock edge)

The write address is registered on the write port clock edge and the data input is written to the memory and mirrored on the output.

Block SelectRAM+ Characteristics

- All inputs are registered with the port clock and have a set-up to clock timing specification.
- All outputs have a read through or write back function depending on the state of the port WE pin. The outputs relative to the port clock are available after the clock-to-out timing specification.
- The block SelectRAMs are true SRAM memories and do not have a combinatorial path from the address to the output. The LUT SelectRAM+ cells in the CLBs are still available with this function.
- The ports are completely independent from each other (*i.e.,* clocking, control, address, read/write function, and data width) without arbitration.
- A write operation requires only one clock edge.
- A read operation requires only one clock edge.

The output ports are latched with a self timed circuit to guarantee a glitch free read. The state of the output port does not change until the port executes another read or write operation.

Library Primitives

Figure 31 and Figure 32 show the two generic library block SelectRAM+ primitives. Table 14 describes all of the available primitives for synthesis and simulation.

VHDL Initialization Example

```
library IEEE;
use IEEE.std_logic_1164.all;

entity MYMEM is
port (CLK, WE:in std_logic;
ADDR: in std_logic_vector(8 downto 0);
DIN: in std_logic_vector(7 downto 0);
DOUT: out std_logic_vector(7 downto 0));
end MYMEM;

architecture BEHAVE of MYMEM is
signal logic0, logic1: std_logic;

component RAMB4_S8
--synopsys translate_off
generic( INIT_00,INIT_01, INIT_02, INIT_03, INIT_04, INIT_05, INIT_06, INIT_07,
INIT_08, INIT_09, INIT_0a, INIT_0b, INIT_0c, INIT_0d, INIT_0e, INIT_0f : BIT_VECTOR(255
downto 0)
:= X"0000000000000000000000000000000000000000000000000000000000000000");
--synopsys translate_on
port (WE, EN, RST, CLK: in STD_LOGIC;
ADDR: in STD_LOGIC_VECTOR(8 downto 0);
DI: in STD_LOGIC_VECTOR(7 downto 0);
DO: out STD_LOGIC_VECTOR(7 downto 0));
end component;

--synopsys dc_script_begin
--set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
--set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
--synopsys dc_script_end

begin
logic0 <='0';
logic1 <='1';

ram0: RAMB4_S8
--synopsys translate_off
generic map (

INIT_00 => X"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF",
INIT_01 => X"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210")
--synopsys translate_on
port map (WE=>WE, EN=>logic1, RST=>logic0, CLK=>CLK,ADDR=>ADDR, DI=>DIN, DO=>DOUT);

end BEHAVE;
```

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUF placement restrictions require that any differential amplifier input signals within a bank be of the same standard. How to specify a specific location for the IBUF via the LOC property is described below. Table 19 summarizes the Virtex-E input standards compatibility requirements.

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element by default activates to ensure a zero hold-time requirement. The NODELAY=TRUE property overrides this default.

When the IBUF does not drive a flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

Table 19: **Xilinx Input Standards Compatibility Requirements**

Rule 1	Standards with the same input V_{CCO}, output V_{CCO}, and V_{REF} can be placed within the same bank.

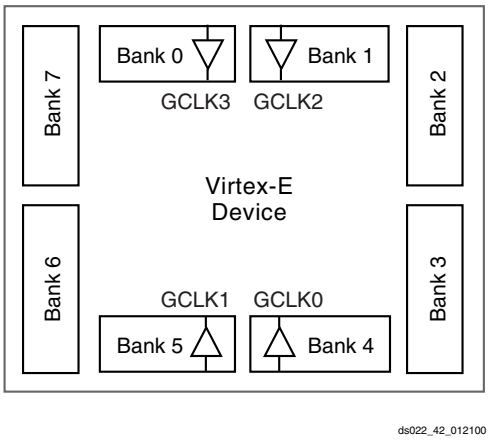


Figure 38: **Virtex-E I/O Banks**

IBUFG

Signals used as high fanout clock inputs to the Virtex-E device should drive a global clock input buffer (IBUFG) via an external input port in order to take advantage of one of the four dedicated global clock distribution networks. The output of the IBUFG should only drive a CLKDLL, CLKDLLHF, or BUFG symbol. The generic Virtex-E IBUFG symbol appears in Figure 39.

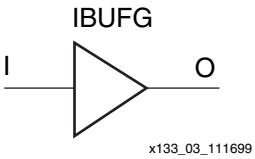


Figure 39: **Virtex-E Global Clock Input Buffer (IBUFG) Symbol**

The extension to the base name determines which I/O standard is used by the IBUFG. With no extension specified for the generic IBUFG symbol, the assumed standard is LVTTL.

The following list details variations of the IBUFG symbol.

- IBUFG
- IBUFG_LVCMOS2
- IBUFG_PCI33_3
- IBUFG_PCI66_3
- IBUFG_GTL
- IBUFG_GTLP
- IBUFG_HSTL_I
- IBUFG_HSTL_III
- IBUFG_HSTL_IV
- IBUFG_SSTL3_I
- IBUFG_SSTL3_II
- IBUFG_SSTL2_I
- IBUFG_SSTL2_II
- IBUFG_CTT
- IBUFG_AGP
- IBUFG_LVCMOS18
- IBUFG_LVDS
- IBUFG_LVPECL

When the IBUFG symbol supports an I/O standard that requires a differential amplifier input, the IBUFG automatically configures as a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}.

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUFG placement restrictions require any differential amplifier input signals within a bank be of the same standard. The LOC property can specify a location for the IBUFG.

As an added convenience, the BUFGP can be used to instantiate a high fanout clock input. The BUFGP symbol

Application Examples

Creating a design with the SelectI/O features requires the instantiation of the desired library symbol within the design code. At the board level, designers need to know the termination techniques required for each I/O standard.

This section describes some common application examples illustrating the termination techniques recommended by each of the standards supported by the SelectI/O features.

Termination Examples

Circuit examples involving typical termination techniques for each of the SelectI/O standards follow. For a full range of accepted values for the DC voltage specifications for each standard, refer to the table associated with each figure.

The resistors used in each termination technique example and the transmission lines depicted represent board level components and are not meant to represent components on the device.

GTL

A sample circuit illustrating a valid termination technique for GTL is shown in Figure 44.

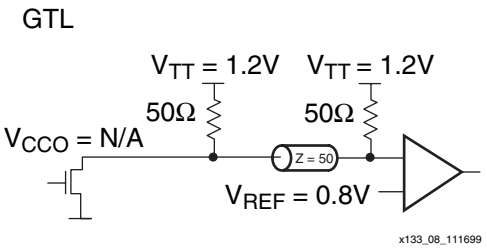


Figure 44: **Terminated GTL**

Table 23 lists DC voltage specifications.

Table 23: **GTL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	-	N/A	-
$V_{REF} = N \times V_{TT}$[1]	0.74	0.8	0.86
V_{TT}	1.14	1.2	1.26
$V_{IH} = V_{REF} + 0.05$	0.79	0.85	-
$V_{IL} = V_{REF} - 0.05$	-	0.75	0.81
V_{OH}	-	-	-
V_{OL}	-	0.2	0.4
I_{OH} at V_{OH}(mA)	-	-	-
I_{OL}at V_{OL}(mA) at 0.4V	32	-	-
I_{OL}at V_{OL}(mA) at 0.2V	-	-	40

Notes:
1. N must be greater than or equal to 0.653 and less than or equal to 0.68.

GTL+

A sample circuit illustrating a valid termination technique for GTL+ appears in Figure 45. DC voltage specifications appear in Table 24.

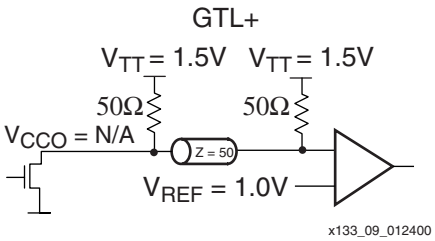


Figure 45: **Terminated GTL+**

Table 24: **GTL+ Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	-	-	-
$V_{REF} = N \times V_{TT}$[1]	0.88	1.0	1.12
V_{TT}	1.35	1.5	1.65
$V_{IH} = V_{REF} + 0.1$	0.98	1.1	-
$V_{IL} = V_{REF} - 0.1$	-	0.9	1.02
V_{OH}	-	-	-
V_{OL}	0.3	0.45	0.6
I_{OH} at V_{OH} (mA)	-	-	-
I_{OL}at V_{OL} (mA) at 0.6V	36	-	-
I_{OL}at V_{OL} (mA) at 0.3V	-	-	48

Notes:
1. N must be greater than or equal to 0.653 and less than or equal to 0.68.

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P173	IO_L16N_Y	2
P171	IO_VREF_L17P_Y	2
P170	IO_L17N_Y	2
P169	IO	2
P168[1]	IO_VREF_L18P_Y	2
P167	IO_D1_L18N_Y	2
P163	IO_D2_L19P_YY	2
P162	IO_L19N_YY	2
P161	IO	2
P160	IO_L20P_Y	2
P159	IO_L20N_Y	2
P157	IO_VREF_L21P_Y	2
P156	IO_D3_L21N_Y	2
P155	IO_L22P_Y	2
P154[3]	IO_VREF_L22N_Y	2
P153	IO_L23P_YY	2
P152	IO_L23N_YY	2
P149	IO	3
P147[3]	IO_VREF	3
P145	IO_D4_L24P_Y	3
P144	IO_VREF_L24N_Y	3
P142	IO_L25P_Y	3
P141	IO_L25N_Y	3
P140	IO	3
P139	IO_L26P_YY	3
P138	IO_D5_L26N_YY	3
P134	IO_D6_L27P_Y	3
P133[1]	IO_VREF_L27N_Y	3
P132	IO	3
P131	IO_L28P_Y	3
P130	IO_VREF_L28N_Y	3
P128	IO_L29P_Y	3
P127	IO_L29N_Y	3
P126[2]	IO_VREF_L30P_Y	3

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P125	IO_L30N_Y	3
P124	IO_D7_L31P_YY	3
P123	IO_INIT_L31N_YY	3
P118	IO_L32P_YY	4
P117	IO_L32N_YY	4
P115[2]	IO_VREF	4
P114	IO_L33P_YY	4
P113	IO_L33N_YY	4
P111	IO_VREF_L34P_YY	4
P110	IO_L34N_YY	4
P109	IO	4
P108[1]	IO_VREF_L35P_YY	4
P107	IO_L35N_YY	4
P103	IO_L36P_YY	4
P102	IO_L36N_YY	4
P101	IO	4
P100	IO_L37P_Y	4
P99	IO_L37N_Y	4
P97	IO_VREF_L38P_Y	4
P96	IO_L38N_Y	4
P95	IO_L39P_Y	4
P94[3]	IO_VREF_L39N_Y	4
P93	IO_LVDS_DLL_L40P	4
P92	GCK0	4
P89	GCK1	5
P87	IO_LVDS_DLL_L40N	5
P86[3]	IO_VREF	5
P84	IO_VREF_L41P_Y	5
P82	IO_L41N_Y	5
P81	IO	5
P80	IO	5
P79	IO_L42P_YY	5
P78	IO_L42N_YY	5

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P138	IO_D5_L26N_YY	3
P137	VCCINT	NA
P136	VCCO	3
P135	GND	NA
P134	IO_D6_L27P_Y	3
P133	IO_VREF_L27N_Y	3
P132	IO_VREF	3
P131	IO_L28P_Y	3
P130	IO_VREF_L28N_Y	3
P129	GND	NA
P128	IO_L29P_Y	3
P127	IO_L29N_Y	3
P126	IO_VREF_L30P_Y	3
P125	IO_L30N_Y	3
P124	IO_D7_L31P_YY	3
P123	IO_INIT_L31N_YY	3
P122	PROGRAM	NA
P121	VCCO	3
P120	DONE	3
P119	GND	NA
P118	IO_L32P_YY	4
P117	IO_L32N_YY	4
P116	VCCO	4
P115	IO_VREF	4
P114	IO_L33P_YY	4
P113	IO_L33N_YY	4
P112	GND	NA
P111	IO_VREF_L34P_YY	4
P110	IO_L34N_YY	4
P109	IO_VREF	4
P108	IO_VREF_L35P_YY	4
P107	IO_L35N_YY	4
P106	GND	NA
P105	VCCO	4
P104	VCCINT	NA
P103	IO_L36P_YY	4

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P102	IO_L36N_YY	4
P101[1]	IO_VREF	4
P100	IO_L37P_Y	4
P99	IO_L37N_Y	4
P98	GND	NA
P97	IO_VREF_L38P_Y	4
P96	IO_L38N_Y	4
P95	IO_L39P	4
P94	IO_VREF_L39N	4
P93	IO_LVDS_DLL_L40P	4
P92	GCK0	4
P91	GND	NA
P90	VCCO	4
P89	GCK1	5
P88	VCCINT	NA
P87	IO_LVDS_DLL_L40N	5
P86	IO_VREF	5
P85	VCCO	5
P84	IO_VREF_L41P	5
P83	GND	NA
P82	IO_L41N	5
P81	IO	5
P80[1]	IO_VREF	5
P79	IO_L42P_YY	5
P78	IO_L42N_YY	5
P77	VCCINT	NA
P76	VCCO	5
P75	GND	NA
P74	IO_L43P_YY	5
P73	IO_VREF_L43N_YY	5
P72	IO_VREF	5
P71	IO_L44P_YY	5
P70	IO_VREF_L44N_YY	5
P69	GND	NA
P68	IO_L45P_YY	5
P67	IO_L45N_YY	5

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
2	IO_D3_L30N _Y	M3
2	IO_L31P	M2
2	IO_L31N	M1
2	IO	N3[1]
2	IO_L32P_YY	N4
2	IO_L32N_YY	N2
3	IO	P1
3	IO	P3[1]
3	IO_L33P	R1
3	IO_L33N	R2
3	IO_D4_L34P _Y	R3
3	IO_VREF_3_L34N _Y	R4
3	IO_L35P_YY	T2
3	IO_L35N_YY	U2
3	IO	T3[1]
3	IO_L36P	T4
3	IO_L36N	V1
3	IO	V2[1]
3	IO_L37P_YY	U3
3	IO_D5_L37N_YY	U4
3	IO_D6_L38P _Y	V3
3	IO_VREF_3_L38N _Y	V4
3	IO_L39P _Y	Y1
3	IO_L39N _Y	Y2
3	IO	W3
3	IO	W4[1]
3	IO	AA1[1]
3	IO_L40P_Y	AA2
3	IO_VREF_3_L40N_Y	Y3
3	IO_L41P_YY	AC1
3	IO_L41N_YY	AB2
3	IO	AA3[1]
3	IO_L42P_YY	AA4

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
3	IO_VREF_3_L42N_YY	AC2[2]
3	IO	AB3
3	IO	AD1[1]
3	IO	AB4[1]
3	IO_D7_L43P_YY	AC3
3	IO_INIT_L43N_YY	AD2
4	IO_L44P_YY	AC5
4	IO_L44N_YY	AD4
4	IO	AE3[1]
4	IO	AD5[1]
4	IO	AC6
4	IO_VREF_4_L45P_YY	AE4[2]
4	IO_L45N_YY	AF3
4	IO	AF4[1]
4	IO_L46P_YY	AC7
4	IO_L46N_YY	AD6
4	IO_VREF_4_L47P_YY	AE5
4	IO_L47N_YY	AE6
4	IO	AD7[1]
4	IO	AE7[1]
4	IO_L48P	AF6
4	IO_L48N	AC9
4	IO	AD8
4	IO_VREF_4_L49P_YY	AE8
4	IO_L49N_YY	AF7
4	IO_L50P_YY	AD9
4	IO_L50N_YY	AE9
4	IO	AD10[1]
4	IO_L51P	AF9
4	IO_L51N	AC11
4	IO	AE10[1]
4	IO_L52P_Y	AD11
4	IO_L52N_Y	AE11

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
6	VCCO	AL31
7	VCCO	A31
7	VCCO	L28
7	VCCO	L31
NA	GND	A2
NA	GND	A3
NA	GND	A7
NA	GND	A9
NA	GND	A14
NA	GND	A18
NA	GND	A23
NA	GND	A25
NA	GND	A29
NA	GND	A30
NA	GND	B1
NA	GND	B2
NA	GND	B30
NA	GND	B31
NA	GND	C1
NA	GND	C31
NA	GND	D16
NA	GND	G1
NA	GND	G31
NA	GND	J1
NA	GND	J31
NA	GND	P1
NA	GND	P31
NA	GND	T4
NA	GND	T28
NA	GND	V1
NA	GND	V31
NA	GND	AC1
NA	GND	AC31
NA	GND	AE1
NA	GND	AE31

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	GND	AH16
NA	GND	AJ1
NA	GND	AJ31
NA	GND	AK1
NA	GND	AK2
NA	GND	AK30
NA	GND	AK31
NA	GND	AL2
NA	GND	AL3
NA	GND	AL7
NA	GND	AL9
NA	GND	AL14
NA	GND	AL18
NA	GND	AL23
NA	GND	AL25
NA	GND	AL29
NA	GND	AL30

Notes:

1. V_{REF} or I/O option only in the XCV600E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV400E, XCV600E; otherwise, I/O option only.

Table 15: **BG560 Differential Pin Pair Summary XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
109	4	AJ14	AK14	√	-
110	4	AM14	AN15	√	VREF
111	4	AJ15	AK15	1	-
112	4	AL15	AM16	7	-
113	4	AL16	AJ16	7	VREF
114	4	AK16	AN17	2	VREF
115	5	AM17	AM18	NA	IO_LVDS_DLL
116	5	AK18	AJ18	7	VREF
117	5	AN19	AL19	7	-
118	5	AK19	AM20	9	-
119	5	AJ19	AL20	√	VREF
120	5	AN21	AL21	√	-
121	5	AJ20	AM22	3	-
122	5	AK21	AN23	√	VREF
123	5	AJ21	AM23	√	-
124	5	AK22	AM24	8	-
125	5	AL23	AJ22	√	-
126	5	AK23	AL24	√	VREF
127	5	AN26	AJ23	13	-
128	5	AK24	AM26	7	VREF
129	5	AM27	AJ24	7	-
130	5	AL26	AK25	5	VREF
131	5	AN29	AJ25	√	VREF
132	5	AK26	AM29	√	-
133	5	AM30	AJ26	11	-
134	5	AK27	AL29	√	VREF
135	5	AN31	AJ27	√	-
136	5	AM31	AK28	12	VREF
137	6	AJ30	AH29	√	-
138	6	AH30	AK31	17	VREF
139	6	AJ31	AG29	14	-

Table 15: **BG560 Differential Pin Pair Summary XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
140	6	AG30	AK32	15	VREF
141	6	AF29	AH31	16	-
142	6	AF30	AH32	15	-
143	6	AH33	AE29	√	VREF
144	6	AE30	AG33	17	VREF
145	6	AF32	AD29	14	-
146	6	AD30	AE31	18	VREF
147	6	AC29	AE32	19	-
148	6	AC30	AD31	√	VREF
149	6	AC31	AB29	√	-
150	6	AB30	AC33	17	-
151	6	AA29	AB31	14	-
152	6	AA31	AA30	15	VREF
153	6	Y29	AA32	16	-
154	6	Y30	AA33	15	-
155	6	W29	Y32	√	VREF
156	6	W31	W30	17	-
157	6	V30	W33	14	-
158	6	V31	V29	18	VREF
159	6	U33	V32	19	VREF
160	7	U32	U31	√	-
161	7	T30	T32	19	VREF
162	7	T31	T29	18	VREF
163	7	R31	R33	14	-
164	7	R29	R30	17	-
165	7	P31	P32	√	VREF
166	7	P29	P30	15	-
167	7	N31	M32	16	-
168	7	L33	N30	15	VREF
169	7	L32	M31	14	-
170	7	L31	M30	17	-

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
4	IO_L43P_Y	P12
4	IO_VREF_L43N_Y	R13[2]
4	IO_L44P_YY	N12
4	IO_L44N_YY	T13
4	IO_VREF_L45P_YY	T12
4	IO_L45N_YY	P11
4	IO_L46P_Y	R12
4	IO_L46N_Y	N11
4	IO_VREF_L47P_YY	T11[1]
4	IO_L47N_YY	M11
4	IO_L48P_YY	R11
4	IO_L48N_YY	T10
4	IO_L49P_Y	R10
4	IO_L49N_Y	M10
4	IO_VREF_L50P_Y	P9
4	IO_L50N_Y	T9
4	IO_L51P_Y	N10
4	IO_L51N_Y	R9
4	IO_LVDS_DLL_L52P	N9
5	GCK1	R8
5	IO	N7
5	IO	T7
5	IO_LVDS_DLL_L52N	T8
5	IO_L53P_Y	R7
5	IO_VREF_L53N_Y	P8
5	IO_L54P_Y	P7
5	IO_L54N_Y	T6
5	IO_L55P_YY	M7
5	IO_L55N_YY	R6
5	IO_L56P_YY	P6
5	IO_VREF_L56N_YY	R5[1]
5	IO_L57P_Y	N6
5	IO_L57N_Y	T5
5	IO_L58P_YY	M6

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
5	IO_VREF_L58N_YY	T4
5	IO_L59P_YY	T3
5	IO_L59N_YY	P5
5	IO_VREF_L60P_Y	T2[2]
5	IO_L60N_Y	N5
6	IO_L61N_YY	M3
6	IO_L61P_YY	R1
6	IO_L62N	M4
6	IO_VREF_L62P	N2[2]
6	IO_L63N_YY	L5
6	IO_L63P_YY	P1
6	IO_VREF_L64N_Y	N1
6	IO_L64P_Y	L3
6	IO_L65N	M2
6	IO_L65P	L4
6	IO_VREF_L66N_Y	M1[1]
6	IO_L66P_Y	K4
6	IO_L67N_YY	L2
6	IO_L67P_YY	L1
6	IO_L68N	K3
6	IO_L68P	K1
6	IO_L69N_YY	K2
6	IO_L69P_YY	K5
6	IO_VREF_L70N_Y	J3
6	IO_L70P_Y	J1
6	IO_L71N	J4
6	IO_L71P	H1
6	IO	J2
7	IO	C2
7	IO_L72N_YY	G1
7	IO_L72P_YY	H4
7	IO_L73N	G5
7	IO_L73P	H2

FG456 Fine-Pitch Ball Grid Array Packages

XCV200E and XCV300E devices in FG456 fine-pitch Ball Grid Array packages have footprint compatibility. Pins labeled I0_VREF can be used as either in both devices provided in this package. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 18, see Table 19 for Differential Pair information.

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
0	GCK3	C11
0	IO	A2[1]
0	IO	A3
0	IO	A6[1]
0	IO	A10
0	IO	B5
0	IO	B9
0	IO	C5
0	IO	D8
0	IO	D10
0	IO	E11[1]
0	IO_L0N	D5
0	IO_L0P	B3
0	IO_VREF_L1N_YY	B4
0	IO_L1P_YY	E6
0	IO_L2N	A4
0	IO_L2P	E7
0	IO_VREF_L3N_YY	C6
0	IO_L3P_YY	D6
0	IO_L4N_Y	A5
0	IO_L4P_Y	B6
0	IO_L5N_Y	D7
0	IO_L5P_Y	C7
0	IO_VREF_L6N_YY	E8
0	IO_L6P_YY	B7
0	IO_L7N_YY	A7
0	IO_L7P_YY	E9
0	IO_L8N_Y	C8
0	IO_L8P_Y	B8
0	IO_L9N_Y	D9
0	IO_L9P_Y	A8
0	IO_L10N	C9
0	IO_L10P	E10
0	IO_VREF_L11N_YY	A9
0	IO_L11P_YY	C10
0	IO_L12N_Y	F11
0	IO_L12P_Y	B10
0	IO_LVDS_DLL_L13N	B11
1	GCK2	A11
1	IO	A12[1]
1	IO	A14
1	IO	B16[1]
1	IO	B19
1	IO	E13
1	IO	E15
1	IO	E16
1	IO	E17[1]
1	IO_LVDS_DLL_L13P	D11
1	IO_L14N_Y	C12
1	IO_L14P_Y	D12
1	IO_L15N_Y	B12
1	IO_L15P_Y	A13
1	IO_L16N_YY	E12
1	IO_VREF_L16P_YY	B13
1	IO_L17N_YY	C13
1	IO_L17P_YY	D13
1	IO_L18N_Y	B14
1	IO_L18P_Y	C14
1	IO_L19N_Y	F12
1	IO_L19P_Y	A15
1	IO_L20N_YY	B15
1	IO_L20P_YY	C15
1	IO_L21N_YY	A16
1	IO_VREF_L21P_YY	E14
1	IO_L22N_Y	D14
1	IO_L22P_Y	C16
1	IO_L23N_Y	D15

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
3	IO_L50N_YY	P19
3	IO_L51P_YY	P18
3	IO_D5_L51N_YY	R21
3	IO_D6_L52P_Y	T22
3	IO_VREF_L52N_Y	R19
3	IO_L53P_Y	U22
3	IO_L53N_Y	R18
3	IO_L54P_YY	T21
3	IO_L54N_YY	V22
3	IO_L55P_YY	T20
3	IO_VREF_L55N_YY	U21
3	IO_L56P_YY	W22
3	IO_L56N_YY	T18
3	IO_L57P_YY	U19
3	IO_VREF_L57N_YY	U20
3	IO_L58P_YY	W21
3	IO_L58N_YY	AA22
3	IO_D7_L59P_YY	Y21
3	IO_INIT_L59N_YY	V19
3	IO	M22
4	GCK0	W12
4	IO	W14
4	IO	Y13
4	IO	Y17
4	IO	AA16[1]
4	IO	AA19
4	IO	AB12[1]
4	IO	AB17
4	IO	AB21[1]
4	IO_L60P_YY	W18
4	IO_L60N_YY	AA20
4	IO_L61P	Y18
4	IO_L61N	V17
4	IO_VREF_L62P_YY	AB20
4	IO_L62N_YY	W17
4	IO_L63P	AA18

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
4	IO_L63N	V16
4	IO_VREF_L64P_YY	AB19
4	IO_L64N_YY	AB18
4	IO_L65P_Y	W16
4	IO_L65N_Y	AA17
4	IO_L66P_Y	Y16
4	IO_L66N_Y	V15
4	IO_VREF_L67P_YY	AB16
4	IO_L67N_YY	Y15
4	IO_L68P_YY	AA15
4	IO_L68N_YY	AB15
4	IO_L69P_Y	W15
4	IO_L69N_Y	Y14
4	IO_L70P_Y	V14
4	IO_L70N_Y	AA14
4	IO_L71P	AB14
4	IO_L71N	V13
4	IO_VREF_L72P_YY	AA13
4	IO_L72N_YY	AB13
4	IO_L73P_Y	W13
4	IO_L73N_Y	AA12
4	IO_L74P_Y	Y12
4	IO_L74N_Y	V12
4	IO_LVDS_DLL_L75P	U12
5	IO	U11[1]
5	IO	V8
5	IO	W5
5	IO	AA3[1]
5	IO	AA9
5	IO	AA10
5	IO	AB4
5	IO	AB7[1]
5	IO	AB8
5	GCK1	Y11
5	IO_LVDS_DLL_L75N	AA11
5	IO_L76P_Y	AB11

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
7	IO	J1
7	IO	J4
7	IO	L2[1]
7	IO_L104N_YY	L3
7	IO_L104P_YY	L4
7	IO_L105N_YY	L5
7	IO_L105P_YY	L1
7	IO_L106N_Y	L6
7	IO_L106P_Y	K2
7	IO_L107N_Y	K4
7	IO_VREF_L107P_Y	K3
7	IO_L108N_YY	K1
7	IO_L108P_YY	K5
7	IO_L109N_YY	J3
7	IO_L109P_YY	J2
7	IO_L110N_YY	J5
7	IO_L110P_YY	H1
7	IO_L111N_YY	H2
7	IO_L111P_YY	H3
7	IO_L112N_Y	G1
7	IO_VREF_L112P_Y	H4
7	IO_L113N_Y	F1
7	IO_L113P_Y	F2
7	IO_L114N_YY	H5
7	IO_L114P_YY	G3
7	IO_L115N_YY	E1
7	IO_VREF_L115P_YY	E2
7	IO_L116N_YY	F3
7	IO_L116P_YY	G5
7	IO_L117N_YY	E3
7	IO_VREF_L117P_YY	D2
7	IO_L118N_YY	F5
7	IO_L118P_YY	C1
2	CCLK	B22
3	DONE	Y19
NA	DXN	Y5

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
NA	DXP	V6
NA	M0	AB2
NA	M1	U5
NA	M2	Y4
NA	PROGRAM	W20
NA	TCK	C4
NA	TDI	B20
2	TDO	A21
NA	TMS	D3
NA	NC	W19
NA	NC	W4
NA	NC	D19
NA	NC	D4
NA	VCCINT	E5
NA	VCCINT	E18
NA	VCCINT	F6
NA	VCCINT	F17
NA	VCCINT	G7
NA	VCCINT	G8
NA	VCCINT	G9
NA	VCCINT	G14
NA	VCCINT	G15
NA	VCCINT	H7
NA	VCCINT	G16
NA	VCCINT	H16
NA	VCCINT	J7
NA	VCCINT	J16
NA	VCCINT	P7
NA	VCCINT	P16
NA	VCCINT	R7
NA	VCCINT	R16
NA	VCCINT	T7
NA	VCCINT	T8
NA	VCCINT	T9
NA	VCCINT	T14

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
4	IO_L154N	AG23
4	IO_L155P_YY	AF22
4	IO_L155N_YY	AE22
4	IO_VREF_L156P_YY	AJ22
4	IO_L156N_YY	AG22
4	IO_L157P	AK24[4]
4	IO_L157N	AD20[3]
4	IO_L158P_YY	AA19
4	IO_L158N_YY	AF21
4	IO_L159P	AH22[4]
4	IO_VREF_L159N	AA18
4	IO_L160P	AG21
4	IO_L160N	AK23
4	IO_L161P_YY	AH21[4]
4	IO_L161N_YY	AD19[4]
4	IO_L162P	AE20
4	IO_L162N	AJ21
4	IO_L163P	AG20
4	IO_L163N	AF20
4	IO_L164P	AC18[4]
4	IO_L164N	AF19[4]
4	IO_L165P_YY	AJ20
4	IO_L165N_YY	AE19
4	IO_VREF_L166P_YY	AK22[1]
4	IO_L166N_YY	AH20
4	IO_L167P	AG19
4	IO_L167N	AB17
4	IO_L168P	AJ19
4	IO_L168N	AD17
4	IO_L169P_YY	AA16
4	IO_L169N_YY	AA17
4	IO_VREF_L170P_YY	AK21
4	IO_L170N_YY	AB16
4	IO_L171P	AG18
4	IO_L171N	AK20
4	IO_L172P	AK19
4	IO_L172N	AD16

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
4	IO_L173P_YY	AE16
4	IO_L173N_YY	AE17
4	IO_VREF_L174P_YY	AG17
4	IO_L174N_YY	AJ17
4	IO_L175P	AD15[4]
4	IO_L175N	AH17[3]
4	IO_VREF_L176P_YY	AG16[2]
4	IO_L176N_YY	AK17
4	IO_LVDS_DLL_L177P	AF16
5	GCK1	AK16
5	IO	AA11[4]
5	IO	AA14[4]
5	IO	AD14[4]
5	IO	AE7[5]
5	IO	AE8[5]
5	IO	AE10[4]
5	IO	AF6[4]
5	IO	AF10[4]
5	IO	AG9[4]
5	IO	AG12[4]
5	IO	AG14[5]
5	IO	AH8[4]
5	IO	AK6[5]
5	IO	AK14[5]
5	IO	AJ13[4]
5	IO	AJ15[4]
5	IO_LVDS_DLL_L177N	AH16
5	IO_L178P_YY	AC15[4]
5	IO_VREF_L178N_YY	AG15[2,3]
5	IO_L179P_YY	AB15
5	IO_L179N_YY	AF15
5	IO_L180P_YY	AA15
5	IO_VREF_L180N_YY	AF14
5	IO_L181P_YY	AH15
5	IO_L181N_YY	AK15
5	IO_L182P	AB14

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
7	IO	E3
7	IO	F1[4]
7	IO	G1[5]
7	IO	G4[5]
7	IO	H3[5]
7	IO	J1[4]
7	IO	J3[4]
7	IO	J4[4]
7	IO	J6[4]
7	IO	L10[4]
7	IO	N2[4]
7	IO	N8[4]
7	IO	N10[4]
7	IO	P3[5]
7	IO	P9[4]
7	IO	R1[5]
7	IO	T3[4]
7	IO_L247P	R10
7	IO_L248N_YY	R5[3]
7	IO_L248P_YY	R6[4]
7	IO_L249N_YY	R8
7	IO_VREF_L249P_YY	R4[2]
7	IO_L250N_YY	R7
7	IO_L250P_YY	R3
7	IO_L251N_YY	P10
7	IO_VREF_L251P_YY	P6
7	IO_L252N_YY	P5
7	IO_L252P_YY	P2
7	IO_L253N	P7
7	IO_L253P	P4
7	IO_L254N_YY	N4
7	IO_L254P_YY	R2
7	IO_L255N_YY	N7
7	IO_VREF_L255P_YY	P1
7	IO_L256N	M6

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
7	IO_L256P	N6
7	IO_L257N_YY	N5
7	IO_L257P_YY	N1
7	IO_L258N_YY	M4
7	IO_L258P_YY	M5
7	IO_L259N	M2
7	IO_VREF_L259P	M1[1]
7	IO_L260N_YY	L4
7	IO_L260P_YY	L2
7	IO_L261N_Y	M7[4]
7	IO_L261P_Y	L5[4]
7	IO_L262N_YY	L1
7	IO_L262P_YY	M8
7	IO_L263N	K2
7	IO_L263P	M9
7	IO_L264N	L3[4]
7	IO_L264P	M10[4]
7	IO_L265N_YY	K5
7	IO_L265P_YY	K1
7	IO_L266N_YY	L6
7	IO_VREF_L266P_YY	K3
7	IO_L267N_YY	L7
7	IO_L267P_YY	K4
7	IO_L268N_YY	L8
7	IO_L268P_YY	J5
7	IO_L269N_YY	K6
7	IO_VREF_L269P_YY	H4
7	IO_L270N_YY	H1
7	IO_L270P_YY	K7
7	IO_L271N	J7
7	IO_L271P	J2
7	IO_L272N_YY	H5
7	IO_L272P_YY	G2
7	IO_L273N_YY	L9
7	IO_VREF_L273P_YY	G5
7	IO_L274N	F3
7	IO_L274P	K8

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
7	IO_L275N_YY	G3
7	IO_L275P_YY	E1
7	IO_L276N_YY	H6
7	IO_L276P_YY	E2
7	IO_L277N	E4
7	IO_VREF_L277P	K9
7	IO_L278N_YY	J8
7	IO_L278P_YY	F4
7	IO_L279N_Y	D1[3]
7	IO_L279P_Y	H7[4]
7	IO_L280N_YY	G6
7	IO_VREF_L280P_YY	C2[1]
7	IO_L281N	D2
7	IO_L281P	F5
7	IO_L282N_YY	D3[4]
7	IO_L282P_YY	K10[3]
2	CCLK	F26
3	DONE	AJ28
NA	DXN	AJ3
NA	DXP	AH4
NA	M0	AF4
NA	M1	AC7
NA	M2	AK3
NA	PROGRAM	AG28
NA	TCK	B3
NA	TDI	H22
2	TDO	D26
NA	TMS	C1
NA	VCCINT	L11
NA	VCCINT	L12
NA	VCCINT	L19
NA	VCCINT	L20
NA	VCCINT	M11
NA	VCCINT	M12
NA	VCCINT	M19

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	VCCINT	M20
NA	VCCINT	N13
NA	VCCINT	N14
NA	VCCINT	N15
NA	VCCINT	N16
NA	VCCINT	N17
NA	VCCINT	N18
NA	VCCINT	P13
NA	VCCINT	P18
NA	VCCINT	R13
NA	VCCINT	R18
NA	VCCINT	T13
NA	VCCINT	T18
NA	VCCINT	U13
NA	VCCINT	U18
NA	VCCINT	V13
NA	VCCINT	V14
NA	VCCINT	V15
NA	VCCINT	V16
NA	VCCINT	V17
NA	VCCINT	V18
NA	VCCINT	W11
NA	VCCINT	W12
NA	VCCINT	W19
NA	VCCINT	W20
NA	VCCINT	Y11
NA	VCCINT	Y12
NA	VCCINT	Y19
NA	VCCINT	Y20
NA	VCCO_0	B6
NA	VCCO_0	M15
NA	VCCO_0	M14
NA	VCCO_0	L15
NA	VCCO_0	L14
NA	VCCO_0	H14
NA	VCCO_0	M13

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	GND	AG27
NA	GND	D27
NA	GND	AF26
NA	GND	E26
NA	GND	F25
NA	GND	AE25
NA	GND	G24
NA	GND	AJ23
NA	GND	AD24
NA	GND	H23
NA	GND	B23
NA	GND	AC23
NA	GND	AB22
NA	GND	V22
NA	GND	N22
NA	GND	AH18
NA	GND	AB18
NA	GND	J18
NA	GND	C18
NA	GND	U17
NA	GND	T17
NA	GND	R17
NA	GND	P17
NA	GND	U16
NA	GND	T16
NA	GND	R16
NA	GND	P16
NA	GND	U15
NA	GND	T15
NA	GND	R15
NA	GND	P15
NA	GND	U14
NA	GND	T14
NA	GND	R14
NA	GND	P14
NA	GND	AH13
NA	GND	AB13

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	GND	J13
NA	GND	C13
NA	GND	V9
NA	GND	N9
NA	GND	J9
NA	GND	AJ8
NA	GND	AC8
NA	GND	H8
NA	GND	AD7
NA	GND	B8
NA	GND	AE6
NA	GND	G7
NA	GND	F6
NA	GND	AF5
NA	GND	E5
NA	GND	AG4
NA	GND	D4
NA	GND	V3
NA	GND	N3
NA	GND	C3
NA	GND	AK2
NA	GND	AH3
NA	GND	AC2
NA	GND	H2
NA	GND	B2
NA	GND	A2
NA	GND	AK1
NA	GND	AJ2
NA	GND	AJ1
NA	GND	A1
NA	GND	B1

Notes:

1. V_{REF} or I/O option only in the XCV1000E and XCV1600E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV1600E; otherwise, I/O option only.
3. I/O option only in the XCV600E.
4. No Connect in the XCV600E.
5. No Connect in the XCV600E, 1000E.

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
1	IO_L66P_Y	E24
1	IO_L67N_YY	A26
1	IO_VREF_L67P_YY	C25
1	IO_L68N_YY	F24
1	IO_L68P_YY	B26
1	IO_L69N	K23[5]
1	IO_L69P	F25[4]
1	IO_L70N_Y	C26
1	IO_VREF_L70P_Y	H24[2]
1	IO_L71N_Y	G24
1	IO_L71P_Y	A27
1	IO_L72N	B27[5]
1	IO_L72P	G25[4]
1	IO_L73N_YY	E26
1	IO_VREF_L73P_YY	C27
1	IO_L74N_YY	J24
1	IO_L74P_YY	B28
1	IO_L75N	K24[5]
1	IO_L75P	H25[4]
1	IO_L76N_Y	D27
1	IO_L76P_Y	F26
1	IO_L77N_Y	G26
1	IO_L77P_Y	C28
1	IO_L78N_YY	E27[5]
1	IO_L78P_YY	J25[4]
1	IO_L79N_YY	A30
1	IO_VREF_L79P_YY	H26
1	IO_L80N_YY	G27
1	IO_L80P_YY	B29
1	IO_L81N_Y	F27
1	IO_L81P_Y	C29
1	IO_L82N_Y	E28
1	IO_VREF_L82P_Y	F28
1	IO_L83N_Y	L25

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
1	IO_L83P_Y	B30
1	IO_L84N	B31
1	IO_L84P	E29
1	IO_WRITE_L85N_YY	A31
1	IO_CS_L85P_YY	D30
2	IO	F31[3]
2	IO	J32
2	IO	K27[3]
2	IO	K31[3]
2	IO	L28[3]
2	IO	L30[3]
2	IO	M32[3]
2	IO	N26
2	IO	N28[3]
2	IO	P25[3]
2	IO	U26[3]
2	IO	U30
2	IO	U32[3]
2	IO	U34
2	IO_D2	M30
2	IO_DOUT_BUSY_L86P_YY	D32
2	IO_DIN_D0_L86N_YY	J27
2	IO_L87P_Y	E31
2	IO_L87N_Y	F30
2	IO_L88P_Y	G29
2	IO_L88N_Y	F32
2	IO_VREF_L89P_Y	E32
2	IO_L89N_Y	G30
2	IO_L90P	M25
2	IO_L90N	G31
2	IO_L91P_Y	L26
2	IO_L91N_Y	D33
2	IO_VREF_L92P_Y	D34